
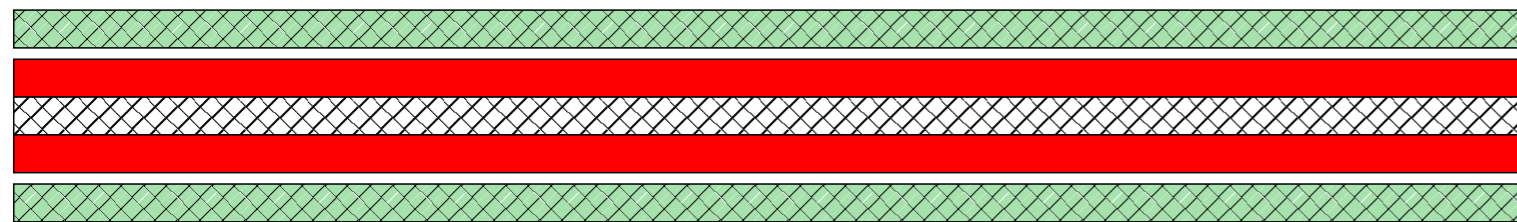


# Rigid

#	Layer	Thickness	Description	Dk	Df	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.105mm	Prepreg IPC-4101/127/128	3,8	0,011	FR-4.1 filled, halogen free
		0.180mm	Prepreg IPC-4101/127/128	3,9	0,011	FR-4.1 filled, halogen free
2	Inner Layer 1	0.017mm	ED Base Copper			
		0.050mm	Flexible core IPC-4204/11	3,4	0,002	Flex Polyimide adhesiveless
3	Inner Layer 2	0.017mm	ED Base Copper			
		0.180mm	Prepreg IPC-4101/127/128	3,9	0,011	FR-4.1 filled, halogen free
		0.105mm	Prepreg IPC-4101/127/128	3,8	0,011	FR-4.1 filled, halogen free
4	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing			
	Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
<b>Total thickness: 0.744mm</b>						

notes:	<b>FLEX4_1Ri-2F-1Ri_0,74_17_V2.12</b>			
Final copper thickness according to IPC-6013	PCB Thickness Tolerance: rigid $\pm 10\%$ / flex $\pm 0,05\text{mm}$			
IPC 2223 use A "Flex to install"	customer		created	
	pcb name		approved	
Please regard to our sectional design rules: ▶ <a href="http://www.we-online.com">www.we-online.com</a>	engineer		format A4, landscape	
	date			
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# Flex



# Layer	Thickness	Description	Dk	Df	Note
1 Flex Top Coverlay	0.040mm	PI Coverlay IPC-4203/2	3,6	0,02	Polyimide + bonding film (Epoxy)
2 Inner Layer 1	0.017mm	ED Base Copper			
3 Inner Layer 2	0.017mm	ED Base Copper			
4 Flex Bottom Coverlay	0.040mm	PI Coverlay IPC-4203/2	3,6	0,02	Polyimide + bonding film (Epoxy)

**Total thickness: 0.164mm**

notes:	<b>FLEX4_1Ri-2F-1Ri_0,74_17_V2.12</b>		
Final copper thickness according to IPC-6013	PCB Thickness Tolerance: rigid $\pm 10\%$ / flex $\pm 0,05\text{mm}$		
IPC 2223 use A "Flex to install"	customer	created	
	pcb name	approved	
Please regard to our sectional design rules: ▶ <a href="http://www.we-online.com">www.we-online.com</a>	engineer	format	A4, landscape
	date		
Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen			

